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## TABLE OF CONTENTS

<b>A 3D Soft-EHL Model for Simulating Feature-scale Defects in Advanced Node ICs .....</b>	1
<i>J. Sierra-Suarez, G. Srivastava, C. Higgs</i>	
<b>Al CMP for Low Resistance Gate Fill for 20nm and Beyond Replacement Metal Gate .....</b>	7
<i>L. Economikos, X. Zhang, H. Hwang, U. Kwon, K. Wong, Y. Escarabajal</i>	
<b>Modeling of ‘Pad-in-a-Bottle’: A Novel Planarization Process Using Suspended Polymer Beads .....</b>	14
<i>W. Fan, J. Johnson, D. Boning</i>	
<b>Progress and Challenges for Chemical Mechanical Polishing of Gallium Nitride .....</b>	24
<i>H. Aida, T. Doi, T. Yamazaki, H. Takeda, K. Koyama</i>	
<b>Characterization of Chemically Modified Thin Films for Optimization of Metal CMP Applications .....</b>	33
<i>G. Basim, A. Karagoz, Z. Ozdemir</i>	
<b>Characteristics in SiC-CMP using MnO<sub>2</sub> Slurry with Strong Oxidant under Different Atmospheric Conditions .....</b>	39
<i>S. Kurokawa, T. Doi, O. Ohnishi, T. Yamazaki, Z. Tan, T. Yin</i>	
<b>3D TSV - Influence Of Electrolyte Composites And Anneal Temperatures To Copper Protrusion And Planarization .....</b>	48
<i>C. Rudolph, H. Wachsmuth, I. Bartusseck, M. Parthenopoulos, L. Goerner, M. Boettcher, J. Grafe, J. Wolf</i>	
<b>Development Of Intelligent Pad And Application To Analysis Of Pressure Distribution On Polishing Pad In CMP Process .....</b>	59
<i>M. Kinoshita, J. Park, H. Jeong</i>	
<b>A Fast, Experimentally validated, Particle Augmented Mixed Lubrication Framework to Predict CMP .....</b>	67
<i>G. Srivastava, C. Higgs III</i>	
<b>Surfactant Mediated Slurry Formulations for Ge CMP Applications .....</b>	73
<i>G. Basim, A. Karagoz, L. Chen, I. Vakarelski</i>	
<b>Reducing Density-Induced CMP Non-Uniformity For Advanced Semiconductor Technology Nodes .....</b>	79
<i>J. Zhang, W. Tseng, T. Chen, B. Kim, P. Flaitz, W. Kleemier, C. Goldberg, C. Truong, S. Grunow</i>	
<b>The Thermal Effects of CMP as a Particle Augmented Mixed Lubrication Tribosystem .....</b>	85
<i>G. Srivastava, C. Higgs III</i>	

**Fluorescence Correlation Spectroscopic Investigation of Surface Adsorption  
of CMP Slurry Additives on Abrasive Particles .....** 90

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**Author Index**